



Everspin Technologies and Teledyne HiRel Semiconductors Partner to Accelerate MRAM Adoption in Aerospace and Defense Applications

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New partnership will bring Everspin 256Mb PERSYST MRAM into Teledyne HiRel Semiconductors' memory solutions for mission-critical systems

CHANDLER, Ariz., & GARLAND, Texas--(BUSINESS WIRE)--Sep. 2, 2026-- Everspin Technologies, Inc. (NASDAQ: MRAM), the world's leading developer and manufacturer of MRAM solutions, and Teledyne HiRel Semiconductors (Teledyne HiRel), a business unit of Teledyne Technologies Incorporated (NYSE: TDY) and a leading supplier of high-reliability semiconductor solutions, today announced a strategic partnership to accelerate adoption of Everspin's MRAM in aerospace, defense and other demanding systems. This collaboration will begin with the 256Mb [PERSYST](#) spin-transfer torque MRAM (STT-MRAM), a non-volatile memory that combines RAM-like speed with the ability to retain data through power loss, system resets and unexpected interruptions.

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Through the new partnership, Teledyne HiRel will initially offer Everspin's 256Mb [PERSYST](#) STT-MRAM as part of its memory products portfolio for military and aerospace customers, with target applications including avionics, VPX and single-board computer platforms, radar and electronic warfare payloads, satellite electronics, autonomous systems and other next-generation electronic solutions. The agreement also covers other [PERSYST](#) STT-MRAM products, including 64Mb and 128Mb options, giving customers additional density choices as program requirements vary.

As component availability, lifecycle planning and long-term supply become greater considerations for programs with long service lives, customers are evaluating persistent memory options that enable fast writes, high endurance and data retention through power loss. These capabilities are especially important for startup, configuration storage, event logging, recovery and other functions that must remain available throughout the product's service life.

Because [PERSYST](#) enables frequent writes with high endurance and retains data without battery backup, it can replace or complement NOR flash in applications that need faster updates or power-loss-safe storage, reducing a program's reliance on battery-backed SRAM, hold-up power or capacitor-backed memory schemes. By combining RAM-like access with non-volatility, MRAM can also help simplify architectures that would otherwise require separate volatile memory, non-volatile storage, backup power, wear-leveling strategies or complex data-protection circuitry. Teledyne HiRel will back this new capability with product guidance, screening flows, qualification documentation, procurement support and obsolescence management.

"Aerospace and defense programs require memory solutions that can sustain long operating lifecycles, documented qualification requirements and reliable performance in harsh environments," said Mont Taylor, Vice President of Business Development at Teledyne HiRel Semiconductors. "By adding Everspin's [PERSYST](#) STT-MRAM to our non-volatile memory portfolio, we give customers a qualified path to specify persistent memory for their most critical applications."

"[PERSYST](#) MRAM delivers a unique combination of endurance, instant-on data retention and high-performance operation," said Sanjeev Aggarwal, President and CEO of Everspin Technologies. "Through our partnership with Teledyne HiRel, customers gain access not only to advanced MRAM technology, but also to the screening expertise and supply continuity needed throughout extended program timelines. This collaboration helps reduce adoption barriers while providing confidence in long-term product availability."

[PERSYST](#) MRAM products will ship from Teledyne HiRel Semiconductors' facility in Milpitas, California, with customer availability anticipated in the fourth quarter of 2026.

About Everspin Technologies

Everspin Technologies, Inc. is the world's leading provider of magnetoresistive RAM (MRAM). Everspin MRAM delivers the industry's most robust, highest-performance, non-volatile memory for Industrial IoT, data centers and other mission-critical applications where data persistence is paramount. Headquartered in Chandler, Arizona, Everspin provides commercially available MRAM solutions to a large and diverse customer base. For more information, visit www.everspin.com.

About Teledyne HiRel Semiconductors and Teledyne Aerospace & Defense Electronics

Teledyne HiRel Semiconductors, part of Teledyne Aerospace & Defense Electronics, delivers high-reliability semiconductor solutions for aerospace, defense, space and industrial applications, with a focus on solving critical customer challenges through standard, semicustom and fully custom offerings. Teledyne Aerospace & Defense Electronics provides a broad portfolio of highly engineered solutions for demanding environments across avionics, energetics, electronic warfare, missiles, radar and surveillance, satellite communications, air and space, and test and measurement.

About Teledyne Technologies

Teledyne Technologies is a leading provider of sophisticated digital imaging products and software, instrumentation, aerospace and defense electronics and engineered systems. Teledyne's operations are primarily located in the United States, the United Kingdom, Canada, and Western and Northern Europe. For more information, visit www.teledyne.com.

Cautionary Statement Regarding Forward-Looking Statements

This press release contains forward-looking statements regarding future events or results. Forward-looking statements are identified by words such as "will," "expects" or similar expressions and include, but are not limited to, statements regarding Everspin's anticipated business plans and business strategy. These forward-looking statements are subject to known and unknown risks, uncertainties, assumptions and other factors that may cause actual results or outcomes to be materially different from any future results or outcomes expressed or implied by the forward-looking statements, including, without limitation, the risks set forth under the caption "Risk Factors" in Everspin's Annual Report on Form 10-K for the year ended December 31, 2025 filed with the SEC on March 5, 2026, as well as in Everspin's subsequent filings with the SEC. Any forward-looking statements made by Everspin in this press release speak only as of the date on which they are made, and subsequent events may cause these expectations to change. Everspin disclaims any obligations to update or alter these forward-looking statements in the future, whether as a result of new information, future events or otherwise, except as required by law.

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